

(0,635 mm) .025"

MEC6-DV SERIES

# VERTICAL MICRO EDGE CARD SOCKET

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?MEC6-DV](http://www.samtec.com?MEC6-DV)

**Insulator Material:**

Black LCP

**Contact Material:**

Phosphor Bronze

**Plating:**

Au or Sn over  
50µ" (1,27 µm) Ni

**Operating Temp Range:**

-55°C to +125°C

**Insertion Depth:**

(4,22 mm) .166" to

(5,66 mm) .223"

**Current Rating:**

1.7 A per pin

(6 adjacent pins powered)

**Voltage Rating:**

210 VAC

**RoHS Compliant:**

Yes

**Processing:**

Lead-Free Solderable:

Yes

**SMT Lead Coplanarity:**

(0,10 mm) .004" max (10-50)

(0,15 mm) .006" max (60-70)

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



## ALSO AVAILABLE (MOQ Required)

- Locking Clip (Manual placement required)
  - Other platings
- Contact Samtec.

**Notes:**

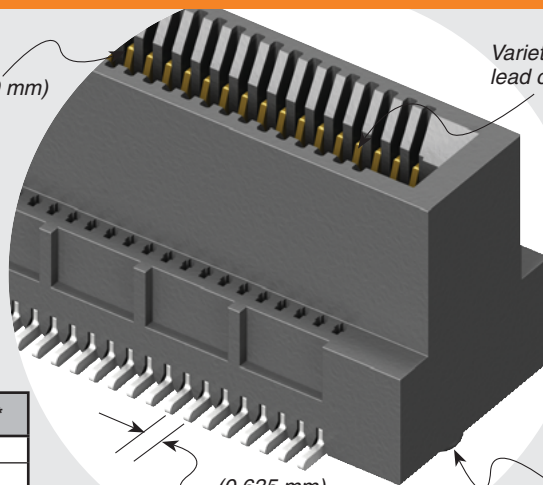
While optimized for 50Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75Ω applications. Contact Samtec for further information.

Some sizes, styles and options are non-standard, non-returnable.

Mates with:  
(1,60 mm) .062" thick cards

Mates with (1,60 mm) .062" thick card

Variety of lead counts

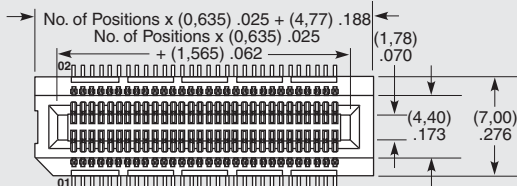
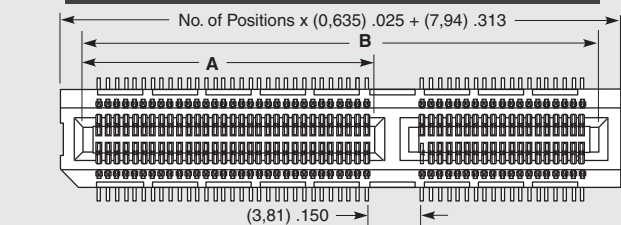
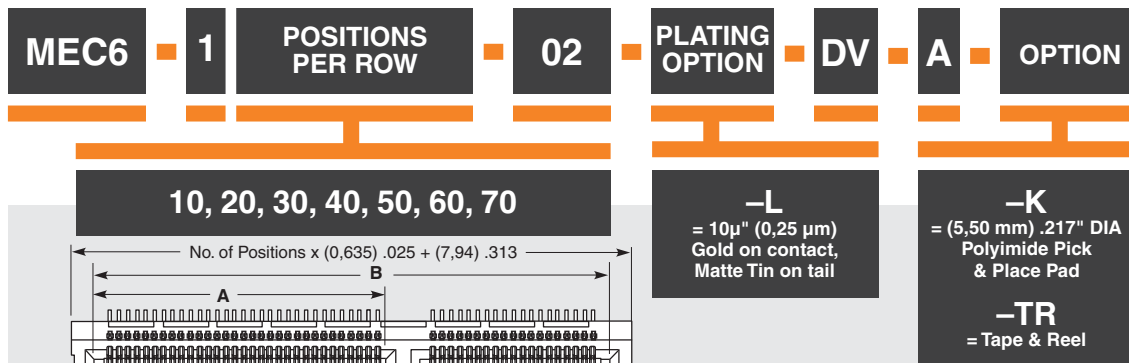


(0,635 mm) .025" pitch

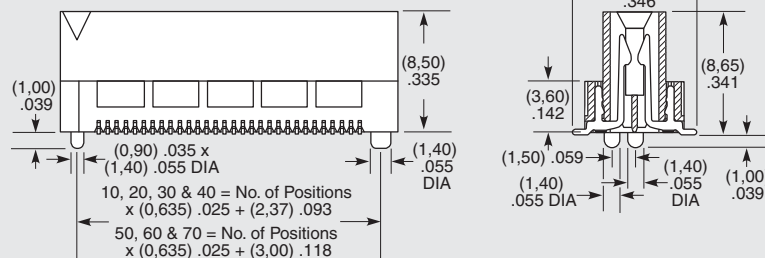
Alignment Pin

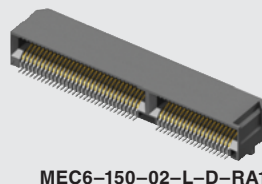
MEC6-DV 8,65 mm Stack Height	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	7.5 GHz / 15 Gbps
Differential Pair Signaling	7.0 GHz / 14 Gbps

\*Performance data includes effects of a non-optimized PCB.  
Complete test data available at [www.samtec.com?MEC6-DV](http://www.samtec.com?MEC6-DV) or contact [sig@samtec.com](mailto:sig@samtec.com)

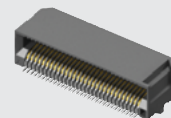
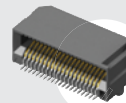


POSITIONS PER ROW	A	B
50	(21,06) .829	(36,49) 1.437
60	(24,87) .979	(42,84) 1.687
70	(28,68) 1.129	(49,19) 1.937





MEC6-120-02-L-D-RA1



MEC6-130-02-L-D-RA1

**MEC6-RA SERIES**

**(0,635 mm) .025"**

# RIGHT ANGLE MICRO EDGE CARD SOCKET

**SPECIFICATIONS**

For complete specifications and recommended PCB layouts see [www.samtec.com?MEC6-RA](http://www.samtec.com?MEC6-RA)

**Insulator Material:**

Black LCP

**Contact Material:**

Phosphor Bronze

**Plating:**

Au or Sn over 50µ" (1,27 µm) Ni

**Operating Temp Range:**

-55°C to +125°C

**Insertion Depth:**

(4,22 mm) .166" to

(5,66 mm) .223"

**Current Rating:**

1.7 A per pin

(6 adjacent pins powered)

**Voltage Rating:**

195 VAC

**RoHS Compliant:**

Yes

**Processing:**

**Lead-Free Solderable:**

Yes

**SMT Lead Coplanarity:**

(0,10 mm) .004" max (10-30)

(0,15 mm) .006" max (40-50)

**RECOGNITIONS**

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



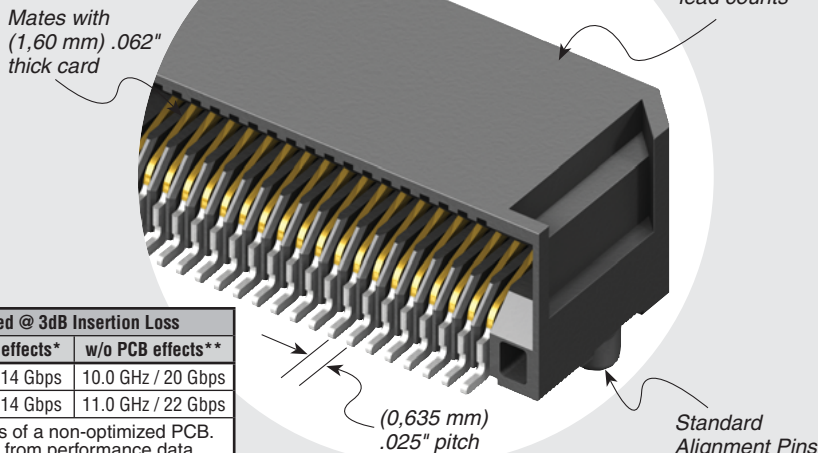
FILE NO. E111594

**Mates with:**

(1,60 mm) .062" thick cards

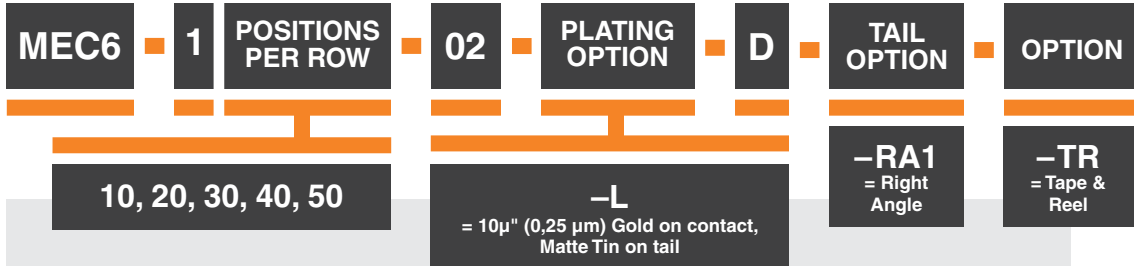
Mates with (1,60 mm) .062" thick card

Variety of lead counts



MEC6-RA	Rated @ 3dB Insertion Loss	
	with PCB effects*	w/o PCB effects**
Single-Ended Signaling	7.0 GHz / 14 Gbps	10.0 GHz / 20 Gbps
Differential Pair Signaling	7.0 GHz / 14 Gbps	11.0 GHz / 22 Gbps

\*Performance data includes effects of a non-optimized PCB.  
 \*\*Test board losses de-embedded from performance data.  
 Complete test data available at [www.samtec.com?MEC6-RA](http://www.samtec.com?MEC6-RA) or contact [sig@samtec.com](mailto:sig@samtec.com)



**ALSO AVAILABLE (MOQ Required)**

- Other platings
- Contact Samtec.

**Note:** While optimized for 50Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75Ω applications. Contact Samtec for further information.

**Note:** Some sizes, styles and options are non-standard, non-returnable.

